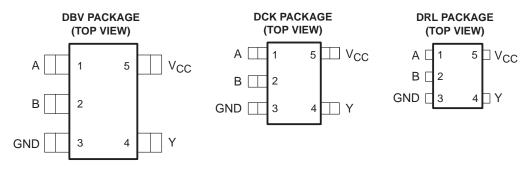
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- Operating Range of 2 V to 5.5 V
- Max t<sub>pd</sub> of 6.5 ns at 5 V
- Low Power Consumption, 10-μA Max I<sub>CC</sub>
- ±8-mA Output Drive at 5 V
- Schmitt Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

### description/ordering information

This device contains a single 2-input NOR gate that performs the Boolean function  $Y = \overline{A} \cdot \overline{B}$  or  $Y = \overline{A + B}$  in positive logic.

#### **ORDERING INFORMATION**

TA	PACKAGI	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>‡</sup>	
		Reel of 3000	SN74AHC1G02DBVR	4.00	
	SOT (SOT-23) – DBV	Reel of 250	SN74AHC1G02DBVT	A02_	
–40°C to 85°C	00T (00 T0) - D0/(	Reel of 3000	SN74AHC1G02DCKR		
	SOT (SC-70) – DCK	Reel of 250	SN74AHC1G02DCKT	AB_	
	SOT (SOT-553) – DRL	Reel of 4000	SN74AHC1G02DRLR	AB_	

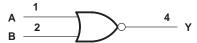
<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

<sup>‡</sup>The actual top-side marking has one additional character that designates the assembly/test site.

FUNCTION TABLE									
INPU	JTS	OUTPUT							
Α	В	Y							
Н	Х	L							
Х	Н	L							
L	L	Н							

## logic diagram (positive logic)



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$ Input voltage range, $V_I$ (see Note 1) Output voltage range, $V_O$ (see Note 1) Input clamp current, $I_{IK}$ ( $V_I < 0$ ) Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) Continuous current through $V_{CC}$ or GND Package thermal impedance, $\theta_{JA}$ (see Note 2): DBV package DCK package	$\begin{array}{ccc} -0.5 \mbox{ V to 7 V} \\0.5 \mbox{ V to V}_{CC} + 0.5 \mbox{ V} \\20 \mbox{ mA} \\ \pm 20 \mbox{ mA} \\ \pm 25 \mbox{ mA} \\ \pm 50 \mbox{ mA} \\ 206^{\circ}\mbox{C/W} \\ 252^{\circ}\mbox{C/W} \end{array}$
	252°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT	
Vcc	Supply voltage		2	5.5	V	
		$V_{CC} = 2 V$	1.5			
ViH	High-level input voltage	$V_{CC} = 3 V$	2.1		V	
		$V_{CC} = 5.5 V$	3.85			
		$V_{CC} = 2 V$		0.5		
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9	V	
		$V_{CC} = 5.5 V$		1.65		
VI	Input voltage		0	5.5	V	
VO	Output voltage		0	VCC	V	
		$V_{CC} = 2 V$		-50	μΑ	
ЮН	High-level output current	$V_{CC}=3.3~V\pm0.3~V$		-4		
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		-8	mA	
		$V_{CC} = 2 V$		50	μΑ	
IOL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4		
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		8	mA	
	land the stilles also as fall as to	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100		
$\Delta t / \Delta v$	Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$		20	ns/V	
ТА	Operating free-air temperature		-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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	TEST CONDITIONS		Тį	<b>₄ = 25°C</b>	;	RAIN I		
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	UNIT
		2 V	1.9	2		1.9		
	l <sub>OH</sub> = -50 μA	3 V	2.9	3		2.9		
VOH		4.5 V	4.4	4.5		4.4		V
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		
	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		
		2 V			0.1		0.1	
	l <sub>OL</sub> = 50 μA	3 V			0.1		0.1	
VOL		4.5 V			0.1		0.1	V
	$I_{OL} = 4 \text{ mA}$	3 V			0.36		0.44	
	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.44	
l	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μA
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			1		10	μA
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4	10		10	pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	Τį	λ = 25°C	;	MINI	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN		
<sup>t</sup> PLH	A or D	Y	0. 45 - 5		5.6	7.9	1	9.5	
<sup>t</sup> PHL	A or B	Y	C <sub>L</sub> = 15 pF		5.6	7.9	1	9.5	ns
<sup>t</sup> PLH	A or B	V	C 50 pF		8.1	11.4	1	13	
<sup>t</sup> PHL	AOLP	T	C <sub>L</sub> = 50 pF		8.1	11.4	1	13	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

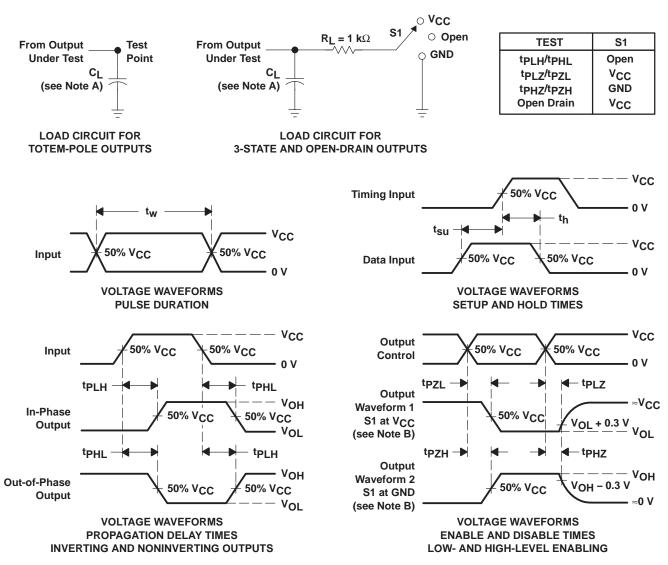
DADAMETED	FROM	то	LOAD	T,	<b>₄ = 25°C</b>	;	MINI		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	A se D	Y	0 45 -5		3.6	5.5	1	6.5	
<sup>t</sup> PHL	A or B	Ŷ	C <sub>L</sub> = 15 pF		3.6	5.5	1	6.5	ns
<sup>t</sup> PLH	A or B	V	$C_{1} = 50 \text{ pF}$		5.1	7.5	1	8.5	
<sup>t</sup> PHL	AUID	T	C <sub>L</sub> = 50 pF		5.1	7.5	1	8.5	ns

## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	15	рF



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## PARAMETER MEASUREMENT INFORMATION

NOTES: A. C<sub>1</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  3 ns, t<sub>f</sub>  $\leq$  3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

#### Figure 1. Load Circuit and Voltage Waveforms



## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AHC1G02DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DCKTG4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DRLR	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G02DRLRG4	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# PACKAGE OPTION ADDENDUM

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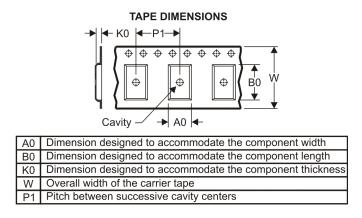
OTHER QUALIFIED VERSIONS OF SN74AHC1G02 : • Enhanced Product: SN74AHC1G02-EP

NOTE: Qualified Version Definitions:

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

## TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC1G02DBVR	SOT-23	DBV	5	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHC1G02DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHC1G02DBVT	SOT-23	DBV	5	250	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHC1G02DCKR	SC70	DCK	5	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHC1G02DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHC1G02DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHC1G02DRLR	SOT	DRL	5	4000	180.0	9.2	1.78	1.78	0.69	4.0	8.0	Q3



# PACKAGE MATERIALS INFORMATION

25-Nov-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC1G02DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74AHC1G02DBVR	SOT-23	DBV	5	3000	565.0	140.0	75.0
SN74AHC1G02DBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
SN74AHC1G02DCKR	SC70	DCK	5	3000	205.0	200.0	33.0
SN74AHC1G02DCKR	SC70	DCK	5	3000	565.0	140.0	75.0
SN74AHC1G02DCKT	SC70	DCK	5	250	565.0	140.0	75.0
SN74AHC1G02DRLR	SOT	DRL	5	4000	202.0	201.0	28.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.

D. Falls within JEDEC MO-178 Variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AA.



DRL (R-PDSO-N5)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. B. This drawing is subject to change without notice.

🖄 Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.





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